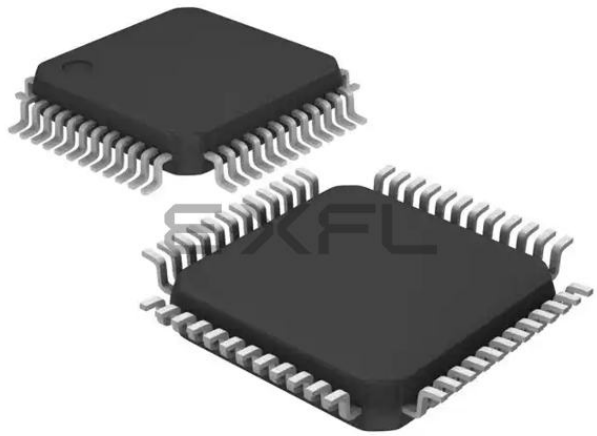

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, Microwire, SmartCard, SPI, SSP, UART/USART, USB
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	40
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	6K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc11u12fbd48-201

Table 3. Pin description *…continued*

Symbol	Pin HVQFN33	Pin LQFP48	Ball TFBGA48	Reset state [1]	Type	Description
TMS/PIO0_12/AD1/ CT32B1_CAP0	22	33	C7 [7]	I; PU	I	**TMS —** Test Mode Select for JTAG interface.
				-	I/O	**PIO_12 —** General purpose digital input/output pin.
				-	I	**AD1 —** A/D converter, input 1.
				-	I	**CT32B1_CAP0 —** Capture input 0 for 32-bit timer 1.
TDO/PIO0_13/AD2/ CT32B1_MAT0	23	34	C8 [7]	I; PU	O	**TDO —** Test Data Out for JTAG interface.
				-	I/O	**PIO0_13 —** General purpose digital input/output pin.
				-	I	**AD2 —** A/D converter, input 2.
				-	O	**CT32B1_MAT0 —** Match output 0 for 32-bit timer 1.
$\overline{\text{TRST}}$/PIO0_14/AD3/ CT32B1_MAT1	24	35	B7 [7]	I; PU	I	**$\overline{\text{TRST}}$ —** Test Reset for JTAG interface.
				-	I/O	**PIO0_14 —** General purpose digital input/output pin.
				-	I	**AD3 —** A/D converter, input 3.
				-	O	**CT32B1_MAT1 —** Match output 1 for 32-bit timer 1.
SWDIO/PIO0_15/AD4/ CT32B1_MAT2	25	39	B6 [7]	I; PU	I/O	**SWDIO —** Serial wire debug input/output.
				-	I/O	**PIO0_15 —** General purpose digital input/output pin.
				-	I	**AD4 —** A/D converter, input 4.
				-	O	**CT32B1_MAT2 —** Match output 2 for 32-bit timer 1.
PIO0_16/AD5/ CT32B1_MAT3/WAKEUP	26	40	A6 [7]	I; PU	I/O	**PIO0_16 —** General purpose digital input/output pin.
				-	I	**AD5 —** A/D converter, input 5.
				-	O	**CT32B1_MAT3 —** Match output 3 for 32-bit timer 1.
				-	I	**WAKEUP —** Deep power-down mode wake-up pin with 20 ns glitch filter. This pin must be pulled HIGH externally to enter Deep power-down mode and pulled LOW to exit Deep power-down mode. A LOW-going pulse as short as 50 ns wakes up the part.
PIO0_17/$\overline{\text{RTS}}$/ CT32B0_CAP0/SCLK	30	45	A3 [3]	I; PU	I/O	**PIO0_17 —** General purpose digital input/output pin.
				-	O	**$\overline{\text{RTS}}$ —** Request To Send output for USART.
				-	I	**CT32B0_CAP0 —** Capture input 0 for 32-bit timer 0.
				-	I/O	**SCLK —** Serial clock input/output for USART in synchronous mode.

Table 3. Pin description *…continued*

Symbol	Pin HVQFN33	Pin LQFP48	Ball TFBGA48	Reset state [1]	Type	Description
PIO0_18/RXD/ CT32B0_MAT0	31	46	B3 [3]	I; PU	I/O	**PIO0_18 —** General purpose digital input/output pin.
				-	I	**RXD —** Receiver input for USART.Used in UART ISP mode.
				-	O	**CT32B0_MAT0 —** Match output 0 for 32-bit timer 0.
PIO0_19/TXD/ CT32B0_MAT1	32	47	B2 [3]	I; PU	I/O	**PIO0_19 —** General purpose digital input/output pin.
				-	O	**TXD —** Transmitter output for USART. Used in UART ISP mode.
				-	O	**CT32B0_MAT1 —** Match output 1 for 32-bit timer 0.
PIO0_20/CT16B1_CAP0	7	9	F2 [3]	I; PU	I/O	**PIO0_20 —** General purpose digital input/output pin.
				-	I	**CT16B1_CAP0 —** Capture input 0 for 16-bit timer 1.
PIO0_21/CT16B1_MAT0/ MOSI1	12	17	G4 [3]	I; PU	I/O	**PIO0_21 —** General purpose digital input/output pin.
				-	O	**CT16B1_MAT0 —** Match output 0 for 16-bit timer 1.
				-	I/O	**MOSI1 —** Master Out Slave In for SSP1.
PIO0_22/AD6/ CT16B1_MAT1/MISO1	20	30	E8 [7]	I; PU	I/O	**PIO0_22 —** General purpose digital input/output pin.
				-	I	**AD6 —** A/D converter, input 6.
				-	O	**CT16B1_MAT1 —** Match output 1 for 16-bit timer 1.
				-	I/O	**MISO1 —** Master In Slave Out for SSP1.
PIO0_23/AD7	27	42	A5 [7]	I; PU	I/O	**PIO0_23 —** General purpose digital input/output pin.
				-	I	**AD7 —** A/D converter, input 7.
PIO1_5/CT32B1_CAP1	-	-	H8 [3]	I; PU	I/O	**PIO1_5 —** General purpose digital input/output pin.
				-	I	**CT32B1_CAP1 —** Capture input 1 for 32-bit timer 1.
PIO1_13/$\overline{\text{DTR}}$/ CT16B0_MAT0/TXD	-	36	B8 [3]	I; PU	I/O	**PIO1_13 —** General purpose digital input/output pin.
				-	O	**$\overline{\text{DTR}}$ —** Data Terminal Ready output for USART.
				-	O	**CT16B0_MAT0 —** Match output 0 for 16-bit timer 0.
				-	O	**TXD —** Transmitter output for USART.

7. Functional description

7.1 On-chip flash programming memory

The LPC11U1x contain up to 32 kB on-chip flash program memory. The flash can be programmed using In-System Programming (ISP) or In-Application Programming (IAP) via the on-chip boot loader software.

7.2 SRAM

The LPC11U1x contain a total of 6 kB on-chip static RAM memory.

7.3 On-chip ROM

The on-chip ROM contains the boot loader and the following Application Programming Interfaces (APIs):

- In-System Programming (ISP) and In-Application Programming (IAP) support for flash programming
- Power profiles for configuring power consumption and PLL settings
- 32-bit integer division routines

7.4 Memory map

The LPC11U1x incorporates several distinct memory regions, shown in the following figures. Figure 5 shows the overall map of the entire address space from the user program viewpoint following reset. The interrupt vector area supports address remapping.

The AHB peripheral area is 2 MB in size and is divided to allow for up to 128 peripherals. The APB peripheral area is 512 kB in size and is divided to allow for up to 32 peripherals. Each peripheral of either type is allocated 16 kB of space. This allows simplifying the address decoding for each peripheral.

7.7.1 Features

- GPIO pins can be configured as input or output by software.
- All GPIO pins default to inputs with interrupt disabled at reset.
- Pin registers allow pins to be sensed and set individually.
- Up to eight GPIO pins can be selected from all GPIO pins to create an edge- or level-sensitive GPIO interrupt request.
- Port interrupts can be triggered by any pin or pins in each port.

7.8 USB interface

The Universal Serial Bus (USB) is a 4-wire bus that supports communication between a host and one or more (up to 127) peripherals. The host controller allocates the USB bandwidth to attached devices through a token-based protocol. The bus supports hot-plugging and dynamic configuration of the devices. All transactions are initiated by the host controller.

The LPC11U1x USB interface consists of a full-speed device controller with on-chip PHY for device functions.

Remark: Configure the LPC11U1x in default power mode with the power profiles before using the USB (see Section 7.16.5.1). Do not use the USB with the part in performance, efficiency, or low-power mode.

7.8.1 Full-speed USB device controller

The device controller enables 12 Mbit/s data exchange with a USB Host controller. It consists of a register interface, serial interface engine, and endpoint buffer memory. The serial interface engine decodes the USB data stream and writes data to the appropriate endpoint buffer. The status of a completed USB transfer or error condition is indicated via status registers. An interrupt is also generated if enabled.

7.8.1.1 Features

- Dedicated USB PLL available.
- Fully compliant with *USB 2.0 specification (full speed)*.
- Supports 10 physical (5 logical) endpoints including one control endpoint.
- Single and double buffering supported.
- Each non-control endpoint supports bulk, interrupt, or isochronous endpoint types.
- Supports wake-up from Deep-sleep mode and Power-down mode on USB activity and remote wake-up.
- Supports SoftConnect.

7.9 USART

The LPC11U1x contains one USART.

The USART includes full modem control, support for synchronous mode, and a smart card interface. The RS-485/9-bit mode allows both software address detection and automatic address detection using 9-bit mode.

- Four match registers per timer that allow:
  - Continuous operation with optional interrupt generation on match.
  - Stop timer on match with optional interrupt generation.
  - Reset timer on match with optional interrupt generation.
- Up to four external outputs corresponding to match registers, with the following capabilities:
  - Set LOW on match.
  - Set HIGH on match.
  - Toggle on match.
  - Do nothing on match.
- The timer and prescaler may be configured to be cleared on a designated capture event. This feature permits easy pulse-width measurement by clearing the timer on the leading edge of an input pulse and capturing the timer value on the trailing edge.

7.14 System tick timer

The ARM Cortex-M0 includes a system tick timer (SYSTICK) that is intended to generate a dedicated SYSTICK exception at a fixed time interval (typically 10 ms).

7.15 Windowed WatchDog Timer (WWDT)

The purpose of the watchdog is to reset the controller if software fails to periodically service it within a programmable time window.

7.15.1 Features

- Internally resets chip if not periodically reloaded during the programmable time-out period.
- Optional windowed operation requires reload to occur between a minimum and maximum time period, both programmable.
- Optional warning interrupt can be generated at a programmable time prior to watchdog time-out.
- Enabled by software but requires a hardware reset or a watchdog reset/interrupt to be disabled.
- Incorrect feed sequence causes reset or interrupt if enabled.
- Flag to indicate watchdog reset.
- Programmable 24-bit timer with internal prescaler.
- Selectable time period from ($T_{cy(WDCLK)} \times 256 \times 4$) to ($T_{cy(WDCLK)} \times 2^{24} \times 4$) in multiples of $T_{cy(WDCLK)} \times 4$.
- The Watchdog Clock (WDCLK) source can be selected from the IRC or the dedicated watchdog oscillator (WDO). This gives a wide range of potential timing choices of watchdog operation under different power conditions.

7.16 Clocking and power control

7.16.1 Integrated oscillators

The LPC11U1x include three independent oscillators. These are the system oscillator, the Internal RC oscillator (IRC), and the watchdog oscillator. Each oscillator can be used for more than one purpose as required in a particular application.

Following reset, the LPC11U1x will operate from the internal RC oscillator until switched by software. This allows systems to operate without any external crystal and the bootloader code to operate at a known frequency.

See Figure 6 for an overview of the LPC11U1x clock generation.

7.17 Emulation and debugging

Debug functions are integrated into the ARM Cortex-M0. Serial wire debug functions are supported in addition to a standard JTAG boundary scan. The ARM Cortex-M0 is configured to support up to four breakpoints and two watch points.

The $\overline{\text{RESET}}$ pin selects between the JTAG boundary scan ($\overline{\text{RESET}}$ = LOW) and the ARM SWD debug ($\overline{\text{RESET}}$ = HIGH). The ARM SWD debug port is disabled while the LPC11U1x is in reset.

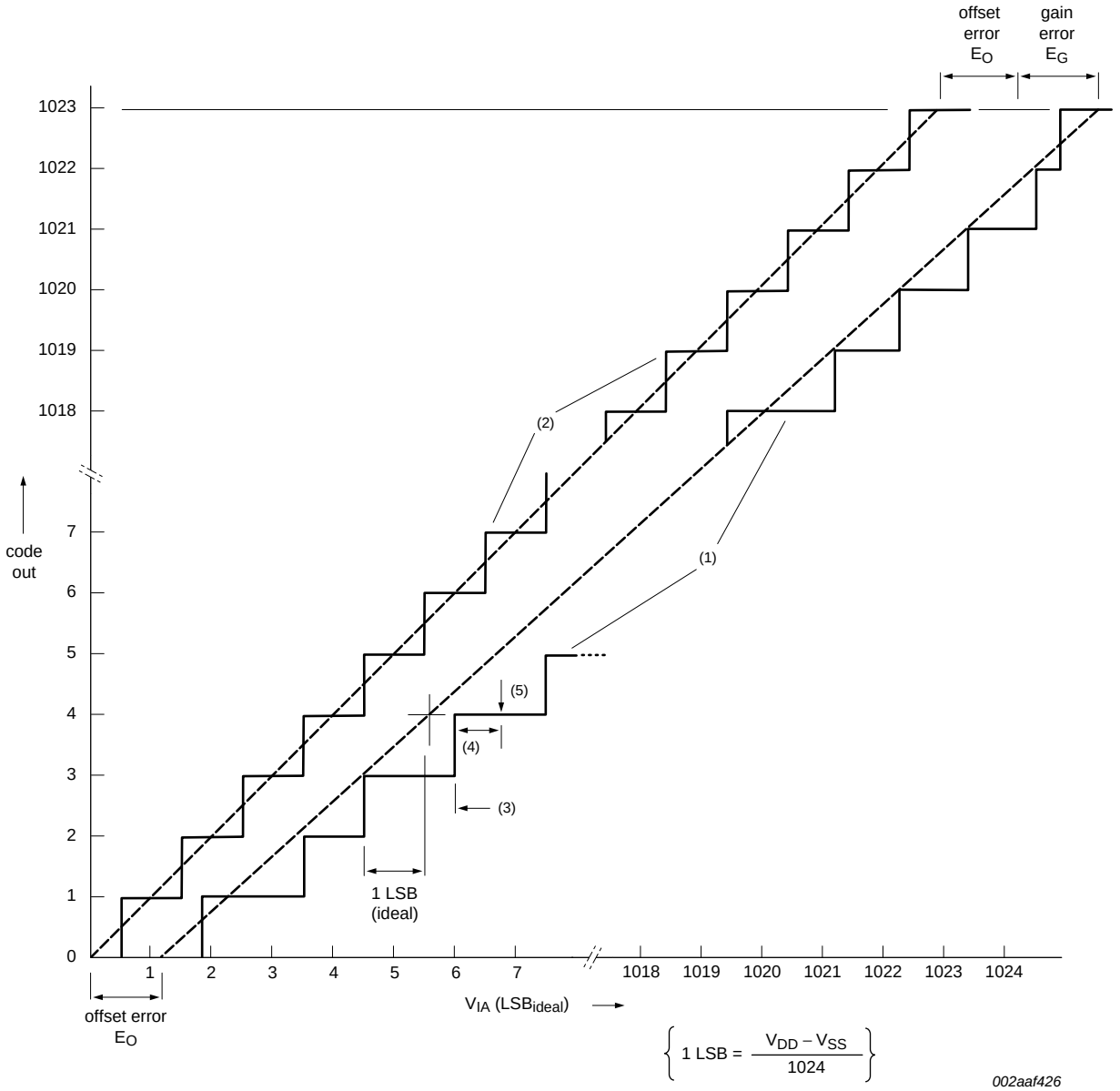
To perform boundary scan testing, follow these steps:

1. Erase any user code residing in flash.
2. Power up the part with the $\overline{\text{RESET}}$ pin pulled HIGH externally.
3. Wait for at least 250 μs.
4. Pull the $\overline{\text{RESET}}$ pin LOW externally.
5. Perform boundary scan operations.
6. Once the boundary scan operations are completed, assert the TRST pin to enable the SWD debug mode and release the $\overline{\text{RESET}}$ pin (pull HIGH).

Remark: The JTAG interface cannot be used for debug purposes.

Table 6. Static characteristics *…continued*
T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
I²C-bus pins (PIO0_4 and PIO0_5)						
V_{IH}	HIGH-level input voltage		$0.7V_{DD}$	-	-	V
V_{IL}	LOW-level input voltage		-	-	$0.3V_{DD}$	V
V_{hys}	hysteresis voltage		-	$0.05V_{DD}$	-	V
I_{OL}	LOW-level output current	V_{OL} = 0.4 V; I²C-bus pins configured as standard mode pins 2.0 V ≤ V_{DD} ≤ 3.6 V	3.5	-	-	mA
		1.8 V ≤ V_{DD} < 2.0 V	3	-	-	
I_{OL}	LOW-level output current	V_{OL} = 0.4 V; I²C-bus pins configured as Fast-mode Plus pins 2.0 V ≤ V_{DD} ≤ 3.6 V	20	-	-	mA
		1.8 V ≤ V_{DD} < 2.0 V	16	-	-	
I_{LI}	input leakage current	V_I = V_{DD} [15]	-	2	4	μA
		V_I = 5 V	-	10	22	μA
Oscillator pins						
$V_{i(xtal)}$	crystal input voltage		−0.5	1.8	1.95	V
$V_{o(xtal)}$	crystal output voltage		−0.5	1.8	1.95	V
USB pins						
I_{OZ}	OFF-state output current	0 V < V_I < 3.3 V [2]	-	-	±10	μA
V_{BUS}	bus supply voltage	[2]	-	-	5.25	V
V_{DI}	differential input sensitivity voltage	|(D+) − (D−)| [2]	0.2	-	-	V
V_{CM}	differential common mode voltage range	includes V_{DI} range [2]	0.8	-	2.5	V
$V_{th(rs)se}$	single-ended receiver switching threshold voltage	[2]	0.8	-	2.0	V
V_{OL}	LOW-level output voltage	for low-/full-speed; R_L of 1.5 kΩ to 3.6 V [2]	-	-	0.18	V
V_{OH}	HIGH-level output voltage	driven; for low-/full-speed; R_L of 15 kΩ to GND [2]	2.8	-	3.5	V
C_{trans}	transceiver capacitance	pin to GND [2]	-	-	20	pF
Z_{DRV}	driver output impedance for driver which is not high-speed capable	with 33 Ω series resistor; steady state drive [16][2]	36	-	44.1	Ω



(1) Example of an actual transfer curve.

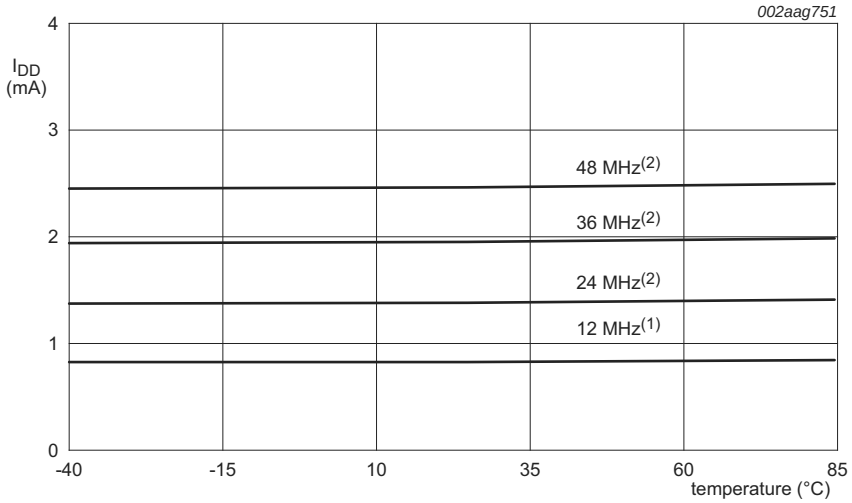
(2) The ideal transfer curve.

(3) Differential linearity error (E_D).

(4) Integral non-linearity ($E_{L(adj)}$).

(5) Center of a step of the actual transfer curve.

Fig 7. ADC characteristics

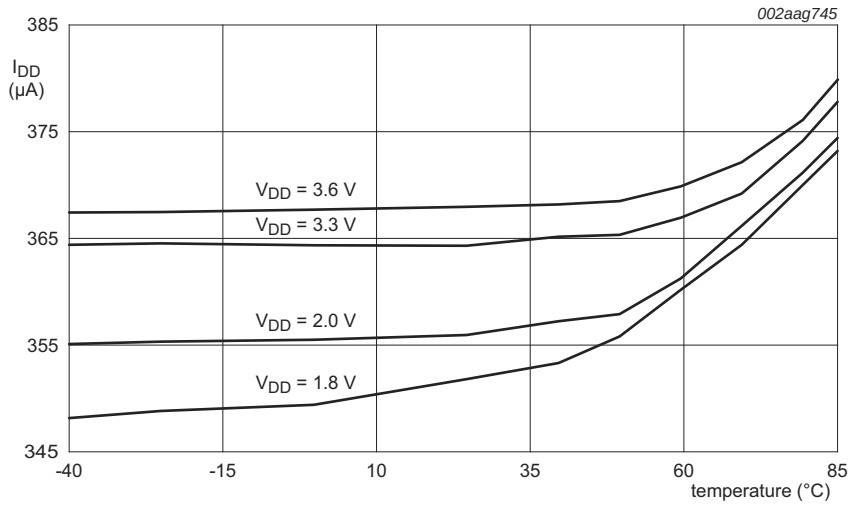


Conditions: V_{DD} = 3.3 V; Sleep mode entered from flash; internal pull-up resistors disabled; BOD disabled; all peripherals disabled in the SYSAHBCLKCTRL register; all peripheral clocks disabled; low-current mode; USB_DP and USB_DM pulled LOW externally.

(1) System oscillator and system PLL disabled; IRC enabled.

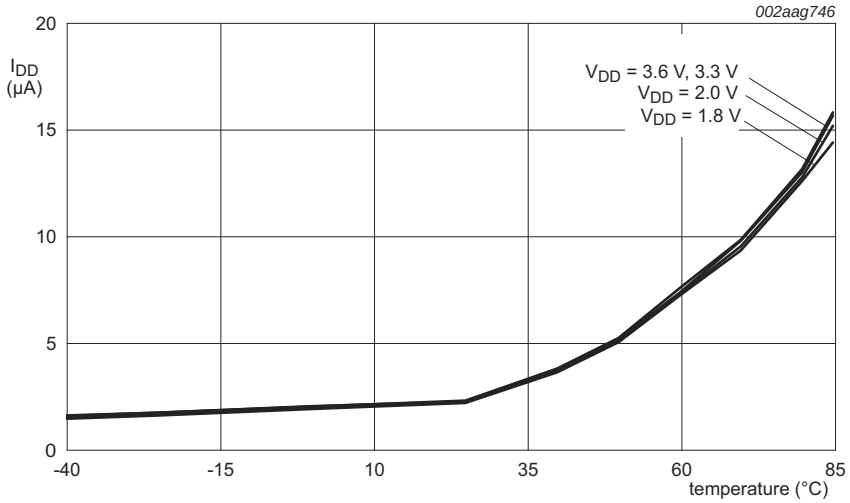
(2) System oscillator and system PLL enabled; IRC disabled.

Fig 10. Typical supply current versus temperature in Sleep mode



Conditions: BOD disabled; all oscillators and analog blocks turned off in the PDSLEEPCFG register; USB_DP and USB_DM pulled LOW externally.

Fig 11. Typical supply current versus temperature in Deep-sleep mode



Conditions: BOD disabled; all oscillators and analog blocks turned off in the PDSLEEPCFG register; USB_DP and USB_DM pulled LOW externally.

Fig 12. Typical supply current versus temperature in Power-down mode

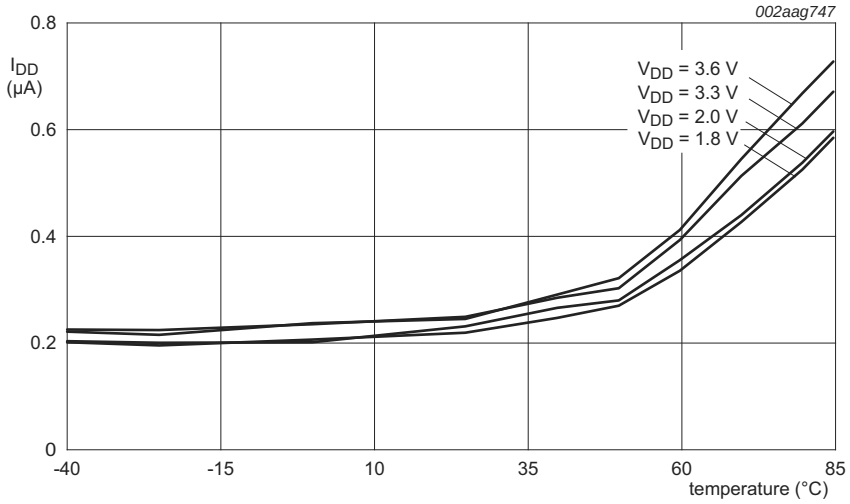


Fig 13. Typical supply current versus temperature in Deep power-down mode

9.3 Peripheral power consumption

The supply current per peripheral is measured as the difference in supply current between the peripheral block enabled and the peripheral block disabled in the SYSAHBCLKCFG and PDRUNCFG (for analog blocks) registers. All other blocks are disabled in both registers and no code is executed. Measured on a typical sample at T_{amb} = 25 °C. Unless noted otherwise, the system oscillator and PLL are running in both measurements.

The supply currents are shown for system clock frequencies of 12 MHz and 48 MHz.

10. Dynamic characteristics

10.1 Flash memory

Table 10. Flash characteristics

T_{amb} = −40 °C to +85 °C, unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
N_{endu}	endurance	[1]	10000	100000	-	cycles
t_{ret}	retention time	powered	10	-	-	years
		unpowered	20	-	-	years
t_{er}	erase time	sector or multiple consecutive sectors	95	100	105	ms
t_{prog}	programming time	[2]	0.95	1	1.05	ms

[1] Number of program/erase cycles.

[2] Programming times are given for writing 256 bytes from RAM to the flash. Data must be written to the flash in blocks of 256 bytes.

10.2 External clock

Table 11. Dynamic characteristic: external clock

T_{amb} = −40 °C to +85 °C; V_{DD} over specified ranges.[1]

Symbol	Parameter	Conditions	Min	Typ[2]	Max	Unit
f_{osc}	oscillator frequency		1	-	25	MHz
$T_{cy(clk)}$	clock cycle time		40	-	1000	ns
t_{CHCX}	clock HIGH time		$T_{cy(clk)} \times 0.4$	-	-	ns
t_{CLCX}	clock LOW time		$T_{cy(clk)} \times 0.4$	-	-	ns
t_{CLCH}	clock rise time		-	-	5	ns
t_{CHCL}	clock fall time		-	-	5	ns

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.

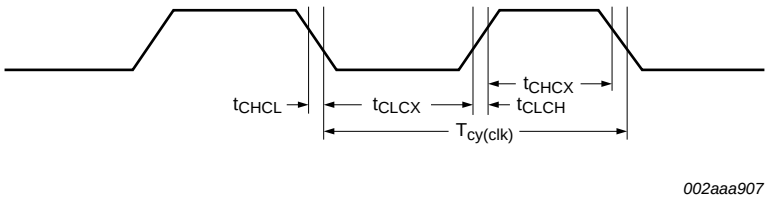


Fig 20. External clock timing (with an amplitude of at least $V_{i(RMS)}$ = 200 mV)

10.3 Internal oscillators

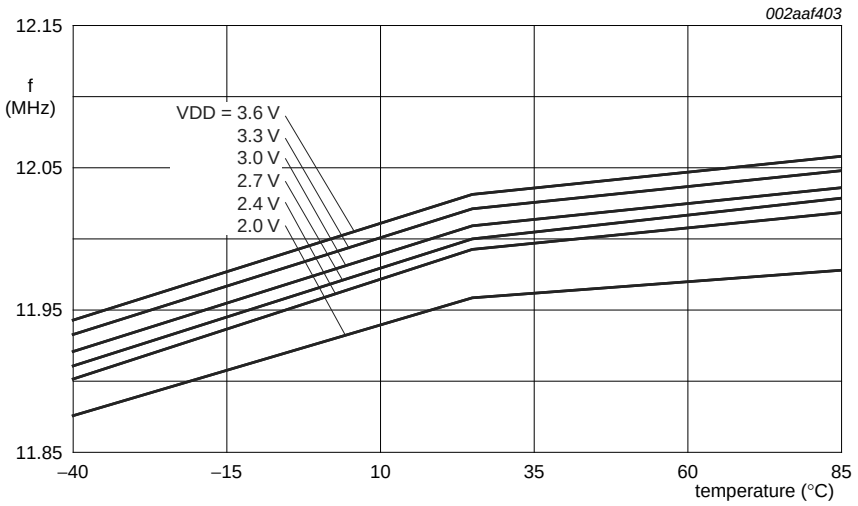
Table 12. Dynamic characteristics: IRC

T_{amb} = −40 °C to +85 °C; 2.7 V ≤ V_{DD} ≤ 3.6 V[1].

Symbol	Parameter	Conditions	Min	Typ[2]	Max	Unit
$f_{osc(RC)}$	internal RC oscillator frequency	-	11.88	12	12.12	MHz

[1] Parameters are valid over operating temperature range unless otherwise specified.

[2] Typical ratings are not guaranteed. The values listed are at room temperature (25 °C), nominal supply voltages.



Conditions: Frequency values are typical values. 12 MHz ± 1 % accuracy is guaranteed for 2.7 V ≤ V_{DD} ≤ 3.6 V and T_{amb} = −40 °C to +85 °C. Variations between parts may cause the IRC to fall outside the 12 MHz ± 1 % accuracy specification for voltages below 2.7 V.

Fig 21. Internal RC oscillator frequency versus temperature

Table 13. Dynamic characteristics: Watchdog oscillator

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Unit
$f_{osc(int)}$	internal oscillator frequency	DIVSEL = 0x1F, FREQSEL = 0x1 in the WDTOSCCTRL register; [2][3]	-	7.8	-	kHz
		DIVSEL = 0x00, FREQSEL = 0xF in the WDTOSCCTRL register [2][3]	-	1700	-	kHz

[1] Typical ratings are not guaranteed. The values listed are at nominal supply voltages.

[2] The typical frequency spread over processing and temperature (T_{amb} = −40 °C to +85 °C) is ±40 %.

[3] See the LPC11U1x *user manual.*

10.4 I/O pins

Table 14. Dynamic characteristics: I/O pins[1]
T_{amb} = −40 °C to +85 °C; 3.0 V ≤ V_{DD} ≤ 3.6 V.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
t_r	rise time	pin configured as output	3.0	-	5.0	ns
t_f	fall time	pin configured as output	2.5	-	5.0	ns

[1] Applies to standard port pins and $\overline{\text{RESET}}$ pin.

10.5 I²C-bus

Table 15. Dynamic characteristic: I²C-bus pins[1]
T_{amb} = −40 °C to +85 °C.[2]

Symbol	Parameter	Conditions	Min	Max	Unit
f_{SCL}	SCL clock frequency	Standard-mode	0	100	kHz
		Fast-mode	0	400	kHz
		Fast-mode Plus	0	1	MHz
t_f	fall time [4][5][6][7]	of both SDA and SCL signals Standard-mode	-	300	ns
		Fast-mode	20 + 0.1 × C_b	300	ns
		Fast-mode Plus	-	120	ns
t_{LOW}	LOW period of the SCL clock	Standard-mode	4.7	-	µs
		Fast-mode	1.3	-	µs
		Fast-mode Plus	0.5	-	µs
t_{HIGH}	HIGH period of the SCL clock	Standard-mode	4.0	-	µs
		Fast-mode	0.6	-	µs
		Fast-mode Plus	0.26	-	µs
$t_{HD;DAT}$	data hold time [3][4][8]	Standard-mode	0	-	µs
		Fast-mode	0	-	µs
		Fast-mode Plus	0	-	µs
$t_{SU;DAT}$	data set-up time [9][10]	Standard-mode	250	-	ns
		Fast-mode	100	-	ns
		Fast-mode Plus	50	-	ns

[1] See the I²C-bus specification *UM10204* for details.

[2] Parameters are valid over operating temperature range unless otherwise specified.

[3] tHD;DAT is the data hold time that is measured from the falling edge of SCL; applies to data in transmission and the acknowledge.

[4] A device must internally provide a hold time of at least 300 ns for the SDA signal (with respect to the V_{IH}(min) of the SCL signal) to bridge the undefined region of the falling edge of SCL.

[5] C_b = total capacitance of one bus line in pF.

[6] The maximum t_f for the SDA and SCL bus lines is specified at 300 ns. The maximum fall time for the SDA output stage t_f is specified at 250 ns. This allows series protection resistors to be connected in between the SDA and the SCL pins and the SDA/SCL bus lines without exceeding the maximum specified t_f.

[7] In Fast-mode Plus, fall time is specified the same for both output stage and bus timing. If series resistors are used, designers should allow for this when considering bus timing.

[8] The maximum $t_{HD;DAT}$ could be 3.45 µs and 0.9 µs for Standard-mode and Fast-mode but must be less than the maximum of $t_{VD;DAT}$ or $t_{VD;ACK}$ by a transition time (see *UM10204*). This maximum must only be met if the device does not stretch the LOW period (t_{LOW}) of the SCL signal. If the clock stretches the SCL, the data must be valid by the set-up time before it releases the clock.

[9] tSU;DAT is the data set-up time that is measured with respect to the rising edge of SCL; applies to data in transmission and the acknowledge.

[10] A Fast-mode I^2C-bus device can be used in a Standard-mode I^2C-bus system but the requirement $t_{SU;DAT}$ = 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line $t_{r(max)} + t_{SU;DAT}$ = 1000 + 250 = 1250 ns (according to the Standard-mode I^2C-bus specification) before the SCL line is released. Also the acknowledge timing must meet this set-up time.

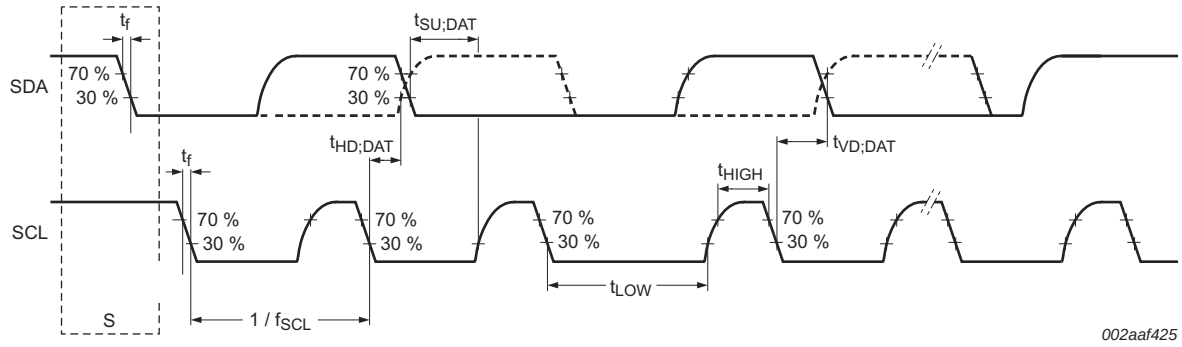


Fig 22. I^2C-bus pins clock timing

Table 18. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters) low frequency mode

Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
1 MHz to 5 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 300 Ω	39 pF, 39 pF
	30 pF	< 300 Ω	57 pF, 57 pF
5 MHz to 10 MHz	10 pF	< 300 Ω	18 pF, 18 pF
	20 pF	< 200 Ω	39 pF, 39 pF
	30 pF	< 100 Ω	57 pF, 57 pF
10 MHz to 15 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 60 Ω	39 pF, 39 pF
15 MHz to 20 MHz	10 pF	< 80 Ω	18 pF, 18 pF

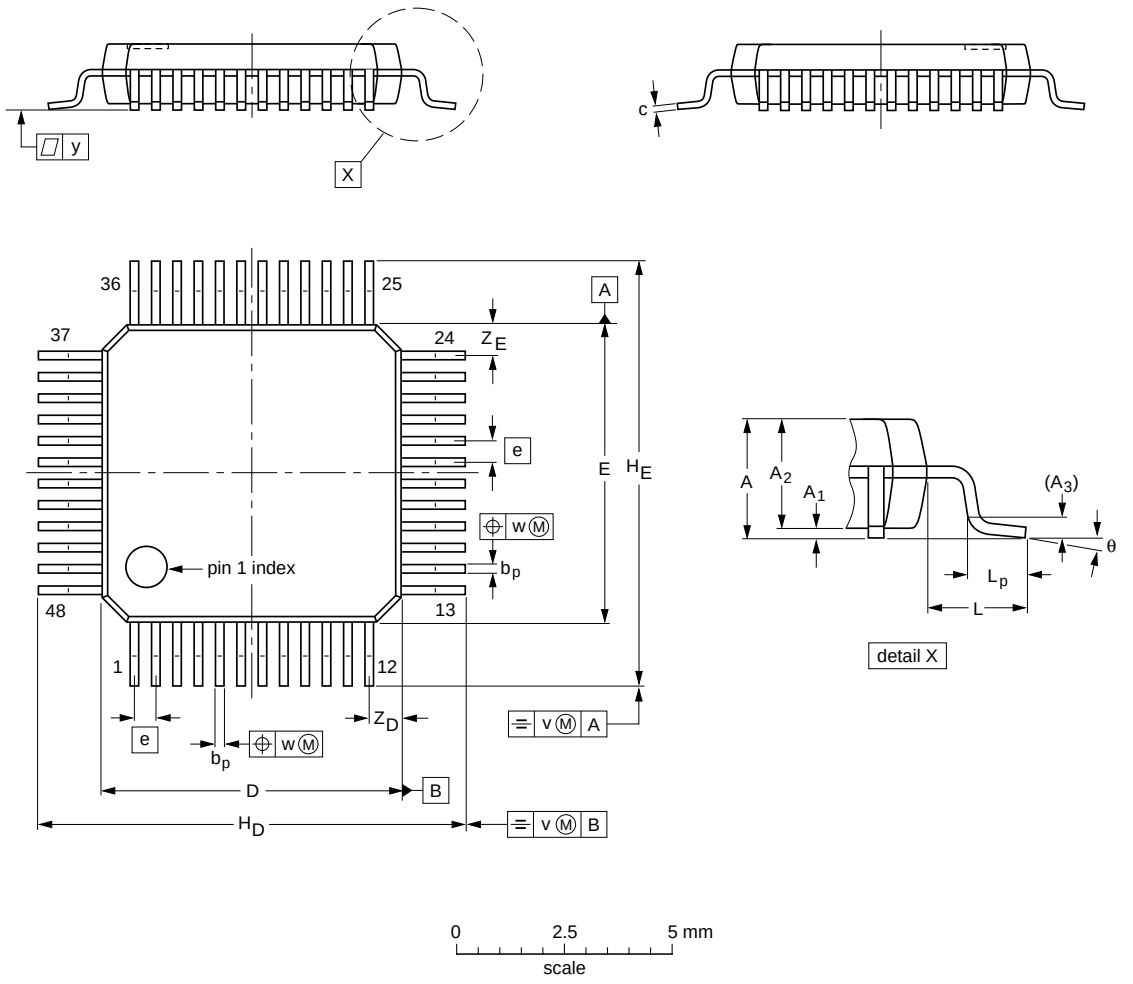
Table 19. Recommended values for C_{X1}/C_{X2} in oscillation mode (crystal and external components parameters) high frequency mode

Fundamental oscillation frequency F_{OSC}	Crystal load capacitance C_L	Maximum crystal series resistance R_S	External load capacitors C_{X1}, C_{X2}
15 MHz to 20 MHz	10 pF	< 180 Ω	18 pF, 18 pF
	20 pF	< 100 Ω	39 pF, 39 pF
20 MHz to 25 MHz	10 pF	< 160 Ω	18 pF, 18 pF
	20 pF	< 80 Ω	39 pF, 39 pF

11.3 XTAL Printed-Circuit Board (PCB) layout guidelines

The crystal should be connected on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors C_{x1}, C_{x2}, and C_{x3} in case of third overtone crystal usage have a common ground plane. The external components must also be connected to the ground plain. Loops must be made as small as possible in order to keep the noise coupled in via the PCB as small as possible. Also parasitics should stay as small as possible. Values of C_{x1} and C_{x2} should be chosen smaller accordingly to the increase in parasitics of the PCB layout.

LQFP48: plastic low profile quad flat package; 48 leads; body 7 x 7 x 1.4 mm **SOT313-2**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_D	H_E	L	L_p	v	w	y	$Z_D^{(1)}$	$Z_E^{(1)}$	θ
mm	1.6	0.20 0.05	1.45 1.35	0.25	0.27 0.17	0.18 0.12	7.1 6.9	7.1 6.9	0.5	9.15 8.85	9.15 8.85	1	0.75 0.45	0.2	0.12	0.1	0.95 0.55	0.95 0.55	7^o 0^o

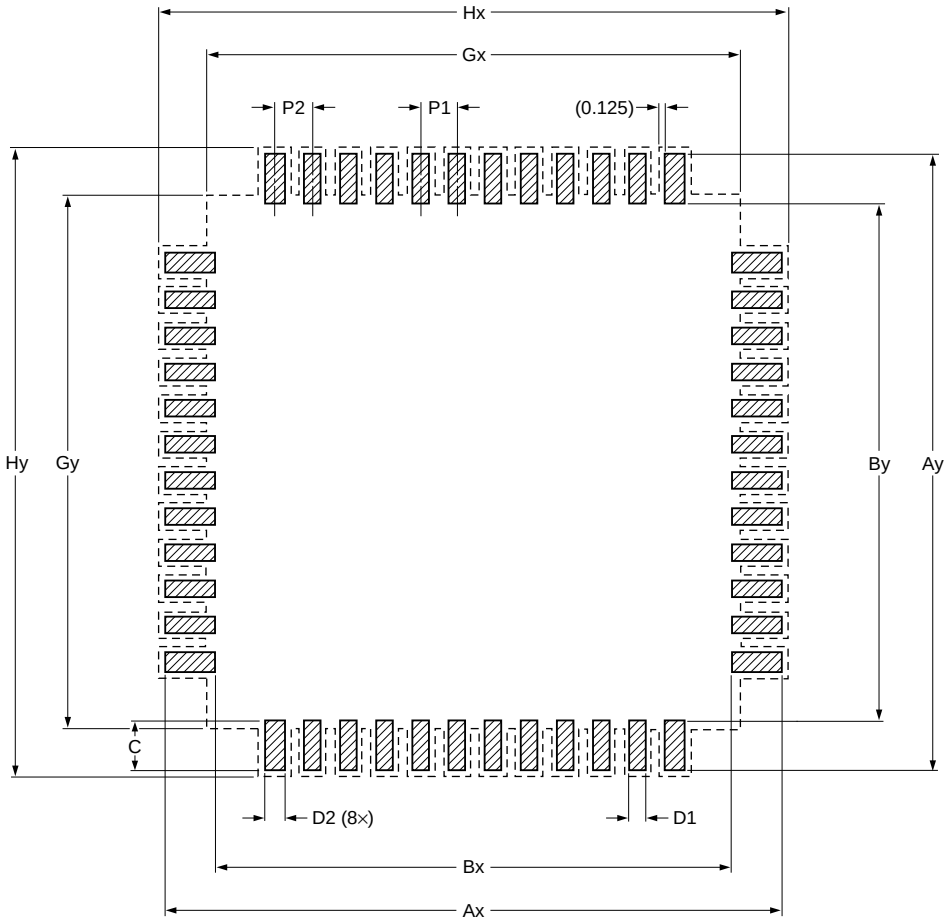
Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT313-2	136E05	MS-026				~~00-01-19~~ 03-02-25

Fig 35. Package outline LQFP48 (SOT313-2)

Footprint information for reflow soldering of LQFP48 package **SOT313-2**



Generic footprint pattern

Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ax	Ay	Bx	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.560	10.350	10.350	7.350	7.350	1.500	0.280	0.500	7.500	7.500	10.650	10.650

sot313-2_fr

Fig 39. Reflow soldering for the LQFP48 package

16. Revision history

Table 21. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
LPC11U1X v.2.2	20140311	Product data sheet	-	LPC11U1X v.2.1
Modifications:	• Updated Section 11.1 “Suggested USB interface solutions” for clarity. • Open-drain I2C-bus and RESET pin descriptions updated for clarity. See Table 3.			
LPC11U1X v.2.1	20130924	Product data sheet	-	LPC11U1X v.2
Modifications:	• Number of CT16B0 match outputs corrected in Figure 1. • Table 3: – Added Table note 2 “5 V tolerant pad” to $\overline{\text{RESET}}$/PIO0_0. – Added Table note 4 “For parts with bootloader version 7.0...” . • Table 8: Removed BOD interrupt level 0. • Added Section 11.6 “ADC effective input impedance”. • Programmable glitch filter is enabled by default. See Section 7.6.1. • Table 6 “Static characteristics” added Pin capacitance section. • Updated Section 11.1 “Suggested USB interface solutions”. • Table 5 “Limiting values”: – Updated V_{DD} min and max. – Updated V_I conditions. • Changed title of Figure 28 from “USB interface on a self-powered device” to “USB interface with soft-connect”. • Section 10.7 “USB interface” added. Parameter t_{EOPR1} and t_{EOPR2} renamed to t_{EOPR}.			
LPC11U1X v.2	20120111	Product data sheet	-	LPC11U1X v.1
Modifications:	• Number of physical and logical endpoints corrected in Section 7.8.1. • Use of JTAG updated in Section 2 (for BSDL only). • Sampling frequency corrected in Table note 7 of Table 7. • Conditions for parameter T_{stg} updated in Table 5. • Part LPC11U14FHI33/201 added. • Editorial updates. • ROM-based integer division routines added (Section 2). • Use of USB with power profiles specified (Section 7.8). • Power consumption data added in Section 9.2. • SSP dynamic characteristics added (Table 16). • IRC dynamic characteristics added (Table 12). • Data sheet status changed to Product data sheet. • Section 13 added. • Description of pin PIO0_3 updated in Table 3: this pin is not used by the boot loader.			
LPC11U1X v.1	20110411	Objective data sheet	-	-

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